

1           ABSTRACT OF THE DISCLOSURE

2           A semiconductor workpiece holder for use in processing a  
3           semiconductor workpiece includes a workpiece support operatively  
4           mounted to support a workpiece in position for processing. A finger  
5           assembly is operatively mounted upon the workpiece support and  
6           includes a finger tip. The finger assembly is movable between an  
7           engaged position in which the finger tip is engaged against the  
8           workpiece, and a disengaged position in which the finger tip is moved  
9           away from the workpiece. Preferably, at least one electrode forms part  
10          of the finger assembly and includes an electrode contact for contacting  
11          a surface of said workpiece. At least one protective sheath covers at  
12          least some of the electrode contact. According to one aspect of the  
13          invention, a sheathed electrode having a sheathed electrode tip is  
14          positioned against a semiconductor workpiece surface in a manner  
15          engaging the workpiece surface with said sheathed electrode tip. A seal  
16          is formed about the periphery of the electrode tip, and with the  
17          electrode tip engaging the workpiece, a desired electrical contact is  
18          made to the workpiece. Thereafter, the workpiece is exposed to  
19          desired semiconductor processing conditions.